

OL-LPC1768UK

WLCSP100: wafer level chip-scale package; 100 balls; 5.074 x 5.074 x 0.6 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	4-11-2013

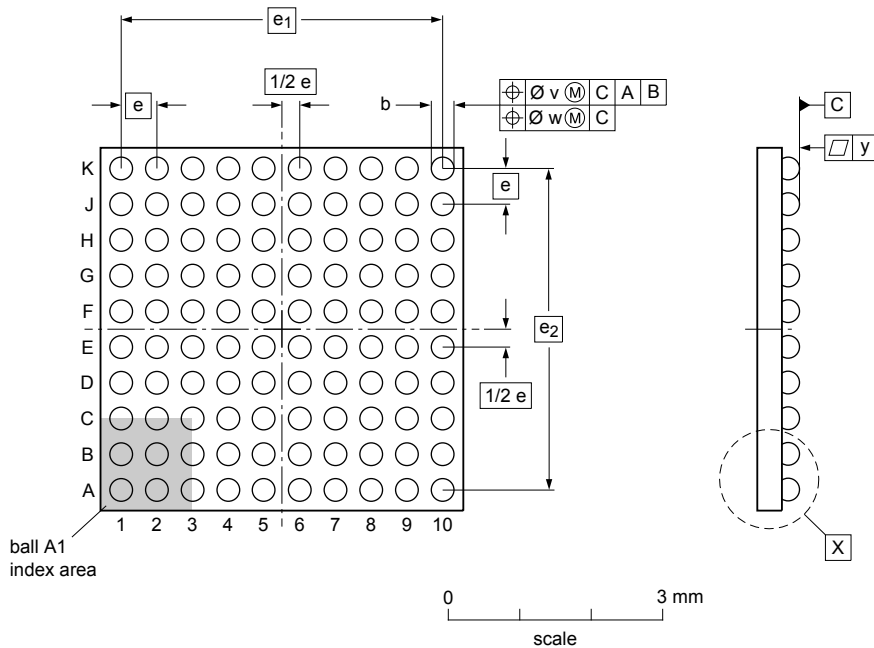
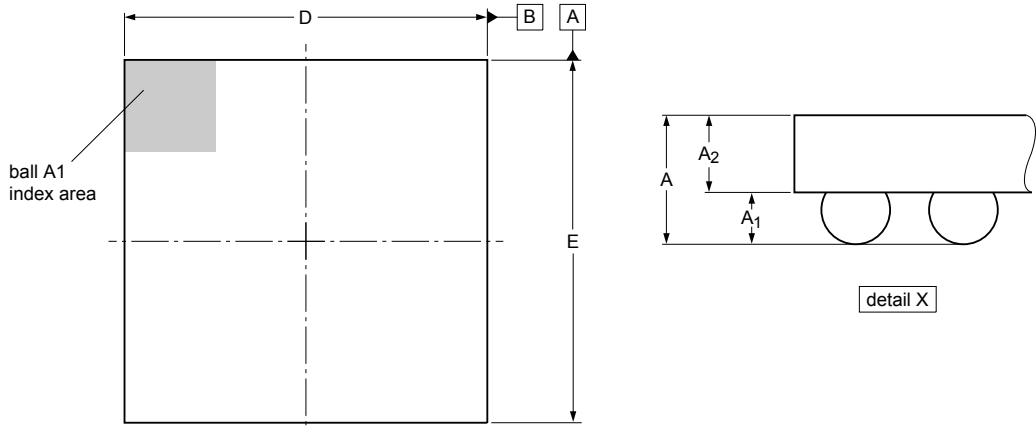
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.044	-	5.074	5.104	mm
E	package width	5.044	-	5.074	5.104	mm
A	seated height	0.55	-	0.6	0.65	mm
A ₂	package height	0.335	-	0.36	0.385	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	100	-	



2. Package outline

WLCSP100: wafer level chip-scale package; 100 balls; 5.074 x 5.074 x 0.6 mm LPC1768UK



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y
max	0.65	0.27	0.385	0.35	5.104	5.104						
mm nom	0.60	0.24	0.360	0.32	5.074	5.074	0.5	4.5	4.5	0.15	0.05	0.05
min	0.55	0.21	0.335	0.29	5.044	5.044						

wlcs100_ipc1768uk_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
LPC1768UK					-11-10-19- 13-11-04

Fig. 1. Package outline WLCSP (OL-LPC1768UK)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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